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Patent Abstracts of Japan

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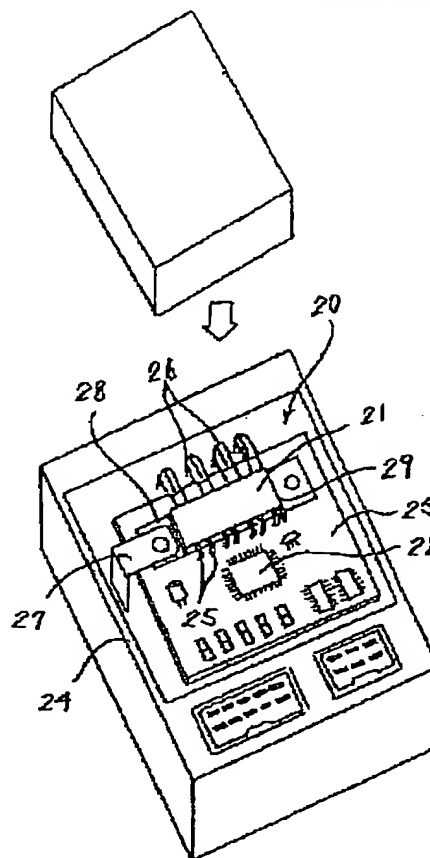
APPLICATION DATE : 14-10-96
APPLICATION NUMBER : 08271204

APPLICANT : YAZAKI CORP;

INVENTOR : OTA KOSEI;

INT.CL. : H02J 1/00 B60R 16/02 H02G 3/16
H02J 7/00

TITLE : POWER SUPPLY DISTRIBUTION FOR
VEHICLE



ABSTRACT : PROBLEM TO BE SOLVED: To reduce the area of a circuit board and facilitate the manufacture of the circuit board by a method wherein the control signal input terminals of respective semiconductor switch chips are connected to signal wiring patterns formed on the circuit board to supply switching control signals to the respective semiconductor switch chips.

SOLUTION: In a vehicle power supply distributor 20, the power supply output terminals 26 of respective semiconductor switches are directly connected to power supply output bus-bars in an electrical junction box without using a circuit board 23. Further, the power supply input terminals of the semiconductor switches are electrically connected to a power supply bus-bar 27 27 which is drawn out of the electrical junction box and directly connected to a metal plate 28 to which a power supply voltage is applied. With this constitution, it is not necessary to form power supply patterns for supplying the power to the respective semiconductor switches and power supply leading out patterns for leading out the power from the respective semiconductor switches on the circuit board 23, so that the circuit area of the circuit board 23 can be reduced and, further, the degree of freedom of the signal wiring patterns can be improved.

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